



Material Content Data Sheet



Sales Product Name				BSC100N06LS3 G		Issued		25. January 2018	
MA#				MA001124052					
Package				PG-TDSON-8-14		Weight*		119.01 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.296	1.09	1.09	10890	10890	
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		82		
	non noble metal	zinc	7440-66-6	0.039	0.03		327		
	non noble metal	iron	7439-89-6	0.778	0.65		6537		
wire	non noble metal	copper	7440-50-8	31.590	26.54	27.23	265442	272388	
	non noble metal	copper	7440-50-8	0.058	0.05	0.05	490	490	
	encapsulation	plastics	epoxy resin	-	7.402	6.22	62195		
leadfinish	inorganic material	silicondioxide	60676-86-0	40.113	33.73		337059		
	organic material	carbon black	1333-86-4	0.239	0.20	40.15	2006	401260	
	non noble metal	tin	7440-31-5	1.243	1.04	1.04	10441	10441	
plating	noble metal	silver	7440-22-4	0.037	0.03	0.03	315	315	
solder	noble metal	silver	7440-22-4	0.037	0.03		309		
	non noble metal	tin	7440-31-5	0.029	0.02		247		
	non noble metal	lead	7439-92-1	1.404	1.18	1.23	11794	12350	
heatspreader	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	zinc	7440-66-6	0.021	0.02		180		
	non noble metal	iron	7439-89-6	0.428	0.36		3593		
heat sink CLIP	non noble metal	copper	7440-50-8	17.360	14.59	14.97	145871	149689	
	non noble metal	iron	7439-89-6	0.017	0.01		142		
	inorganic material	phosphorus	7723-14-0	0.005	0.00		43		
*deviation	non noble metal	copper	7440-50-8	16.898	14.20	14.21	141992	142177	
						Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com